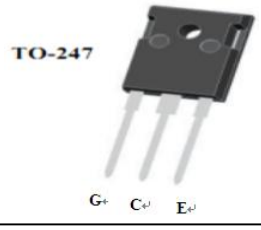
Silicon FS Trench IGBT

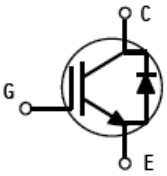
BT25T120 CKR

General Description:

Using HUAJING's proprietary trench design, advanced FS(field stop) technology and integrated with Free Wheeling Diode, the 1200V Trench FS IGBT offers superior conduction and switching performances, high avalanche ruggedness.

V_{CES}	1200	V
I_C	25	A
P_{tot} (T_C=25℃)	312	W
$V_{CE(SAT)}$	1.95	V





Features:

- Trench FS Technology, Positive temperature coefficient
- Low saturation voltage: $V_{CE(sat)}$, typ =1.95V
  @ I_C =25A and T_C = 25°C
- Extremely enhanced avalanche capability

Applications:

Power switch circuit of induction cooker(IH).

Absolute Maximum Ratings

（Tc= 25℃ unless otherwise specified）:

Symbol	Parameter	Rating	Units
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate- Emitter Voltage	±20	V
I_C	Collector Current	50	A
	Collector Current @TC = 100 °C	25	A
I_{CM}[a1]	Pulsed Collector Current	75	A
I_F	Diode Continuous Forward Current @TC = 100 °C	25	A
I_{FM}	Diode Maximum Forward Current	75	A
P_D	Power Dissipation @ TC = 25°C	312	W
	Power Dissipation @TC = 100 °C	125	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	-55 to +150	℃
T_L	Maximum Temperature for Soldering	300	℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction to case for IGBT	--	0.8	℃/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	--	40	℃/W

Electrical Characteristics of the IGBT（Tc= 25℃ unless otherwise specified）：

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V_{CES}	Collector-Emitter Breakdown Voltage	V_{GE}=0V,I_{CE}=1mA	1200	--	--	V
I_{CES}	Collector-Emitter Leakage Current	V_{GE} =0V,V_{CE}=V_{CES}	--	--	1.0	mA
$I_{GES(F)}$	Gate to Emitter Forward Leakage	V_{GE} =+20V	--	--	+250	nA
$I_{GES(R)}$	Gate to Source Reverse Leakage	V_{GE} =-20V	--	--	-250	nA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	I_C=25A,V_{GE}=15V	--	1.95	2.5	V
V_{FM}	Diode Forward Voltage	I_F=15A	--	2.7	3.2	V
$V_{GE(TH)}$	Gate Threshold Voltage	I_C=250uA,V_{CE}=V_{ge}	4.5	5.8	7.5	V
Pulse width tp≤300μs,δ≤2%						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
C_{ies}	Input Capacitance	V_{CE}=30V,V_{GE}=0V f=1MHz	--	2370		pF
C_{oes}	Output Capacitance		--	59		
C_{res}	Reverse Transfer Capacitance		--	43		

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	V_{CE}=600V,I_C=25A V_{GE}=15V, R_g=10Ω Inductive Load	--	34.33		ns
tr	Rise Time		--	35.82		
$t_{d(OFF)}$	Turn-Off Delay Time		--	197.8		
t_f	Fall Time		--	75.41		
Eon	Turn-On Switching Loss		--	1.882		mJ
Eoff	Turn-Off Switching Loss		--	0.945		
Ets	Total Switching Loss		--	2.827		
Q_g	Total Gate Charge	V_{CE}=960V,I_C=25A V_{GE}=15V	--	142		nC
Q_{ge}	Gate to Emitter Charge		--	23		
Q_{gc}	Gate to Collector Charge		--	75		

Characteristics Cure

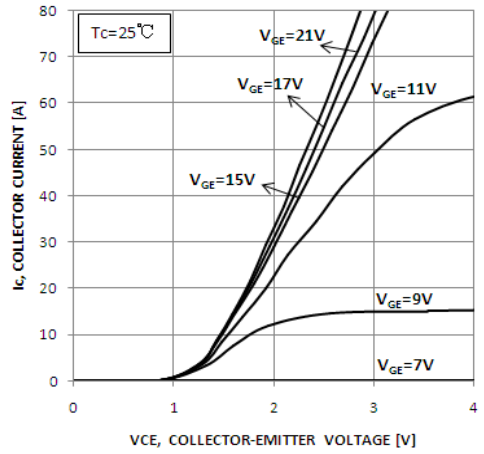


Figure 1. Saturation Voltage Characteristics

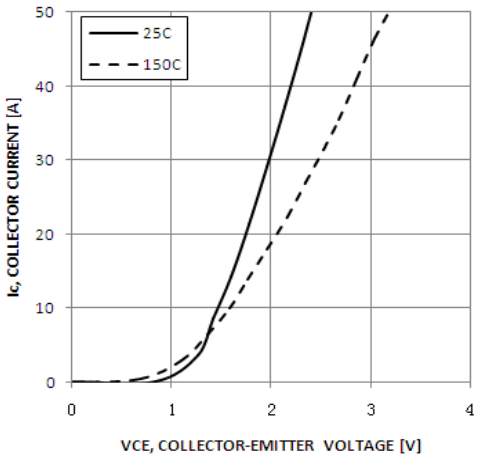


Figure 2. Saturation Voltage Characteristics

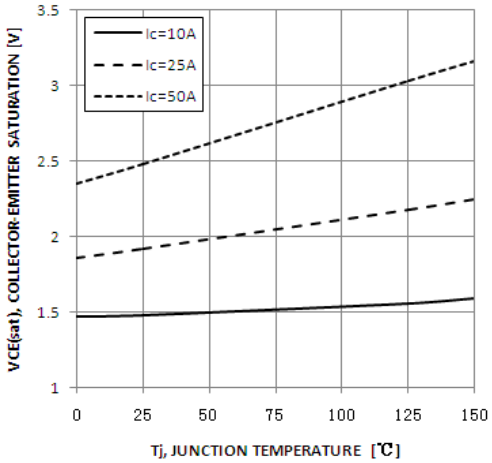


Figure 3. Saturation Voltage vs. Case Temperature

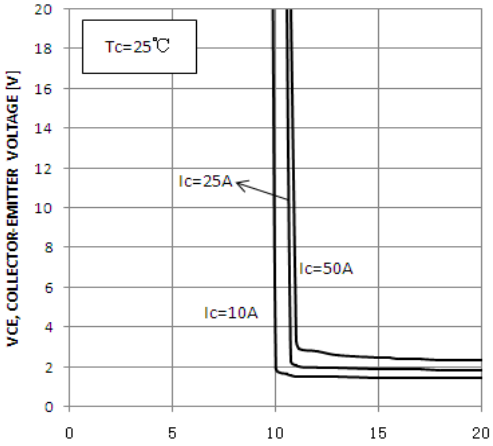


Figure 4. Saturation Voltage vs. V_{GE}

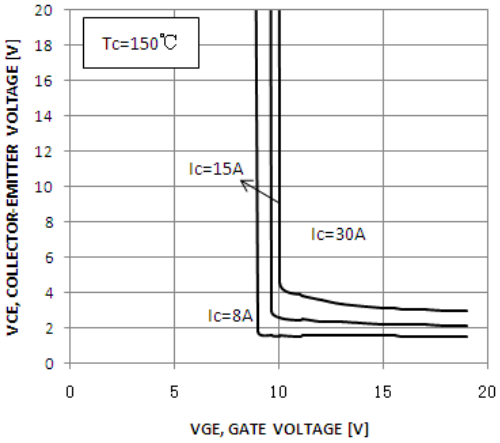


Figure 5. Saturation Voltage vs. V_{GE}

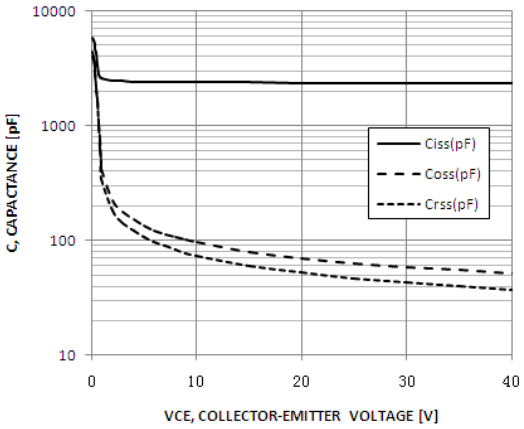


Figure 6. Capacitance Characteristics

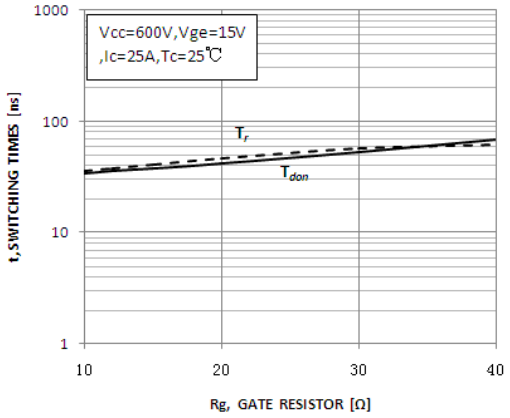


Figure 7. Turn-On Characteristics vs. Gate Resistance

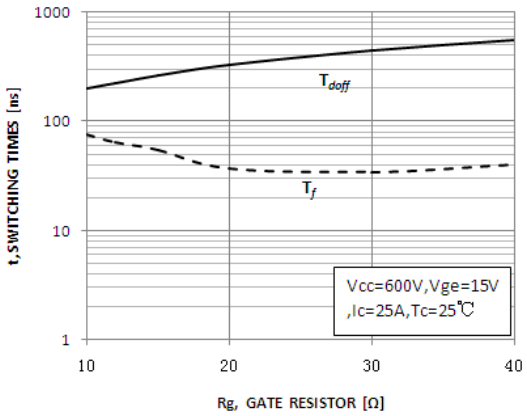


Figure 8. Turn-Off Characteristics vs. Gate Resistance

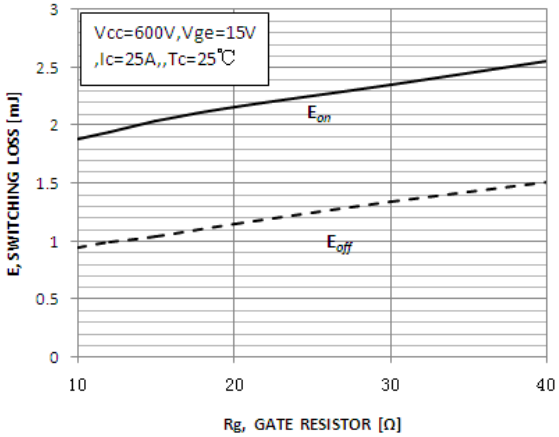


Figure 9. Switching Loss vs. Gate Resistance

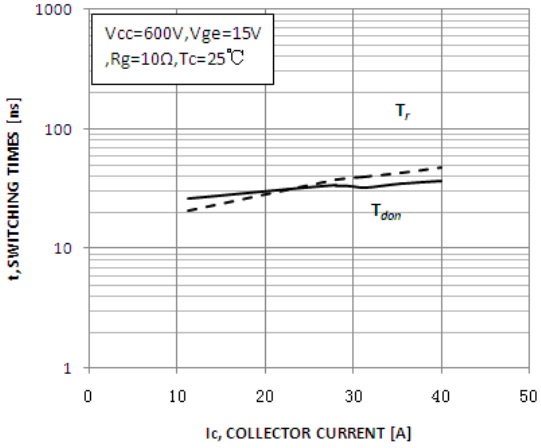


Figure 10. Turn-On Characteristics vs. Collector Current

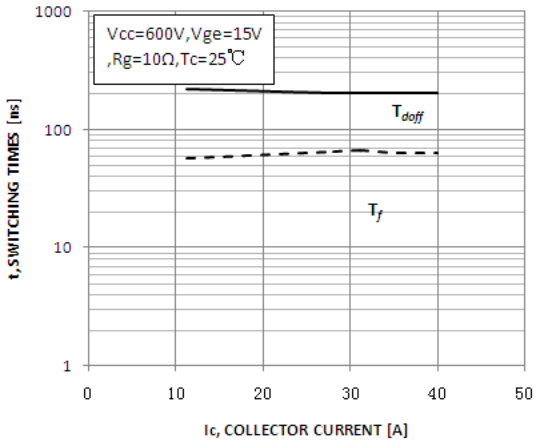


Figure 11. Turn-Off Characteristics vs. Collector Current

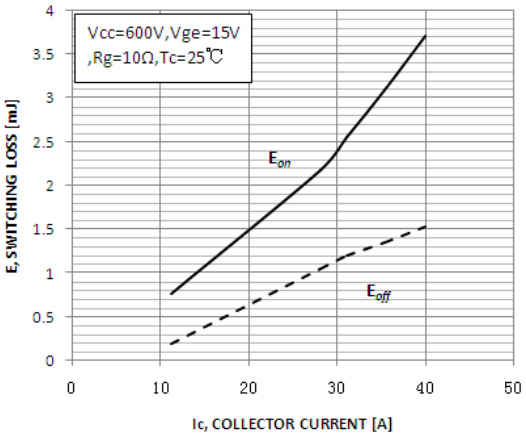


Figure 12. Switching Loss vs. Collector Current

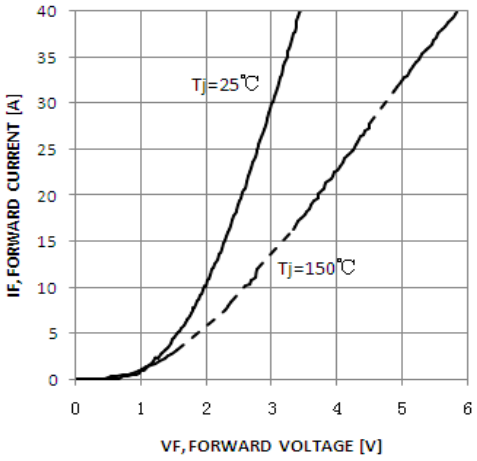


Figure 13. Forward Characteristics

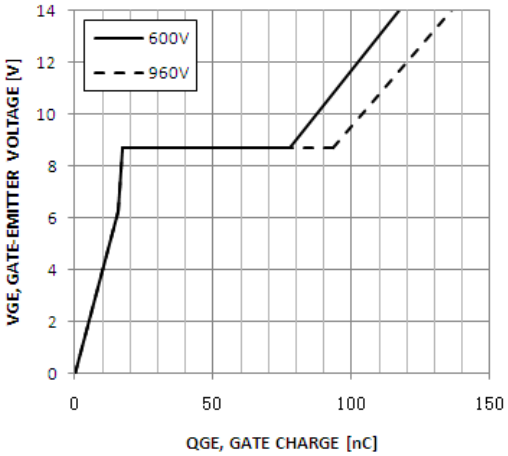


Figure 14. Typical Gate Charge

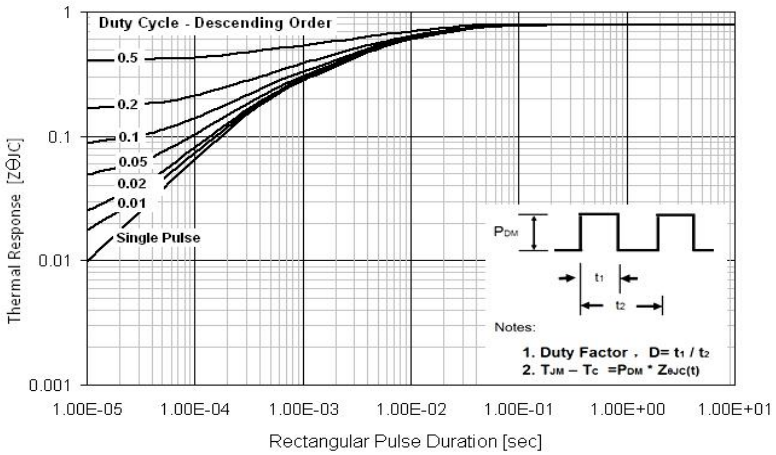
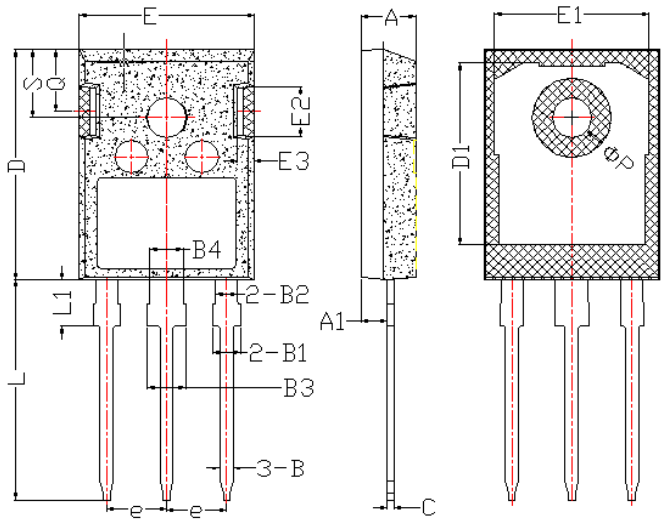


Figure 15. Transient Thermal Impedance of IGBT

Package Information



Items	Values(mm)	
	MIN	MAX
A	4.6	5.2
A1	2,2	2.6
B	0.9	1.4
B1	1.75	2.35
B2	1.75	2.15
B3	2.8	3.35
B4	2.8	3.15
C	0.5	0.7
D	20.60	21.30
D1	16	18
E	15.5	16.10
E1	13	14.7
E2	3.80	5.3
E3	0.8	2.60
e	5.2	5.7
L	19	20.5
L1	3.9	4.6
ΦP	3.3	3.70
Q	5.2	6.00
S	5.8	6.6

TO-247 Package

The name and content of poisonous and harmful material in products

Part's Name	Hazardous Substance									
	Pb	Hg	Cd	Cr(VI)	PBB	PBDE	DIBP	DEHP	DBP	BBP
Limit	≤ 0.1%	≤ 0.1%	≤ 0.01%	≤0.1%	≤0.1%	≤0.1%	≤0.1%	≤0.1%	≤0.1%	≤0.1%
Lead Frame	○	○	○	○	○	○	○	○	○	○
Molding	○	○	○	○	○	○	○	○	○	○
Chip	○	○	○	○	○	○	○	○	○	○
Wire Bonding	○	○	○	○	○	○	○	○	○	○
Solder	×	○	○	○	○	○	○	○	○	○
Note	○：Means the hazardous material is under the criterion of 2011/65/EU. ×：Means the hazardous material exceeds the criterion of 2011/65/EU. The plumbum element of solder exist in products presently, but within the allowed range of Eurogroup's RoHS.									

Warnings

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. It is suggested to be used under 80 percent of the maximum ratings of the device.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. IGBTs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. This publication is made by Huajing Microelectronics and subject to regular change without notice.

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